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PHOTOIMAGEABLE SOLDER MASK

R-500 ORG / HD-5

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1. FEATURES

- (1) For screen printing.
- (2) Excellent in adhesion.
- (3) Suitable to general printed circuit boards and coating film has an outstanding heat resistance.

2. SPECIFICATION

Main agent	R-500 ORG
Hardener	HD – 5
Color	Orange
Mixing ratio	Main agent : 860g / Hardener : 140g
Viscosity	190 ± 30 ps (R type viscometer at 25°C)
Solid content	75~80 wt%
Specific gravity	1.3 ± 0.2
Tack- dry window	75°C x 70 min (maximum)
Exposure energy	300 – 500 mJ / cm² (on the solder)
* Pot life	24 hours (stored at 25°C or below in dark place)
Shelf life	6 months after manufacturing (stored at 25°C or below in dark place)

*After mixing with hardener.

3. PROCESS CONDITIONS

Surface treatment : Acid treatment → Brushing

Coating : Screen printing with 90 - 120 mesh screen

Hold time : 10 - 20 min.

Tack dry : A. One side each exposure
 - 1st side; 70 - 75°C / 15 - 20 min. (Hot air convention oven)
 - 2nd side; 70 - 75°C / 20 - 30 min. (Hot air convention oven)
 B. Both sides simultaneous exposure
 - 70 - 75°C / 35 - 50 min. (Hot air convention oven)

Exposure : 300 - 500 mJ / cm² (on the solder)

Hold time : 10 - 30 min.

Development : Developer ; 1wt% Na₂CO₃
 Temperature ; 29 - 31°C
 Spray pressure ; 2.5 - 3.0 kg / cm²
 Dwell time ; 70 - 100 sec.

Water rinse : Temp. 30°C or below
 Spray pressure ; 1 - 1.5 kg / cm²
 Dwell time ; 45 - 60 sec.

Post cure : Non plugging ;
 150 - 160 °C / 60 min. (Hot air convention oven)
 Plugging ;
 80°C x 30min→110°C x 30 分→160°C x 60min (Hot air convention oven)

4. CHARACTERISTIC

(1). TACK DRY WINDOW

Tack dry window (min. @75°C)	40	50	60	70	80	90
Developability	○	○	○	○	△	×

(2). HOLD TIME

Hold time (hrs)	24	36	48	72
Developability	○	○	○	×

(Holding at 20°C / 60%RH after drying at 75°C / 25 mins.)

(3).PHOTOSENSITIVITY

Item	Thickness	Energy	Dwell time	Sensitivity
Sensitivity	25 μ m	300 mJ/cm ²	60sec	9 - 11wedges
Stouffer		400 mJ/cm ²		10- 12wedges
(2lsteps tablet)		500 mJ/cm ²		11 - 13wedges

Exposure energy is measured at under Mylar film.

5. PROPERTIES

Item	Test method	Result
Adhesion	Cross Cut Adhesion Tester (Simex Cat No.01-903-01)	100/100
Pencil hardness	Pencil Hardness Tester (Yasuda/NO.553-M)	≥6H
Solder heat resistance	Rosin flux 260°C / 30sec, 1cycles	Pass
Solvent resistance	PGM-Ac, room temp./30min Cross hatch peeling	Pass
Acid resistance	10vol% H ₂ SO ₄ , room temp./20min Cross hatch peeling	Pass
Alkaline resistance	10wt% NaOH, room temp./20min Cross hatch peeling	Pass
Electroless gold plate	NI; 125 μ inch Au; 3 μ inch	Pass

Note : The all test data mentioned in this technical data sheet are based on our laboratory tests and only for reference, we suggest testing for suitability in your application.

6. R-500 ORG COMPLY WITH IPC-SM-840C ClassH

Property	Test Method	Requirement	Test Result
3.4.8. Visual	Magnifying lens rated between 1.75 to 10X magnification	No cracks No peeling and roughness. Free of foreign materials.	OK
3.5.2.1. Adhesion (tape method)	Determined in accordance with TM2.4.28.1 of IPC-TM-650. Differentiation of class shall be required.	Bare Copper $\leq 0\%$ Gold or Nickel $\leq 5\%$ Base Laminate $\leq 0\%$ Melting Metals $\leq 10\%$ (Tin-Lead plating)	PASSED PASSED PASSED PASSED
3.5.3. Mashinability	Subjected to drilling, routing, sawing or punching.	No cracks, No peeling and roughness.	PASSED
3.5.1.. Pencil Method	45degree angle, forward pressure in a 1/4 inch.	No softer than "F"	PASSED/6H
3.4.5. Curing	3.6.1.1.Resistance to Solvents and Cleaning Agents. 3.7.1.Solderability. 3.7.2.solder resistance.	Must meet requirements of 3.6.1., 3.7.2.and 3.7.3.	PASSED PASSED PASSED
3.6.1. Resistance to solvents, Cleaning Agents, Flux	<ul style="list-style-type: none"> Isopropanol room temperature 2 minutes. 75%Isopropanol/25%water 46±2°c 15 minutes. room temperature. D-Limonene room temperature 2 minutes. 10% Alkaline detergent EXP. $\leq 40\%$ alkanolamine $\leq 20\%$ 2-butoxyethanol $\leq 20\%$ glycol ether and the remaining 90% water (PH=13 or less) 57±2°c 2 minutes. Monoethanolamine 57±2°c 2 minutes Deionized water 60±2°c 2 minutes 	No surface roughness, blisters, delamination,swelling, and color change.	PASSED PASSED PASSED PASSED
3.6.3. Flammability	UL-94 flammability.	UL-94 V number shall not be raised.	94 V-0
3.7.1. Solderbilty	After flux coated, hold at ambient temperature for 5 minutes, preheat and solder float at 255±5°C for 10±1 seconds.	Solderbilty of boads shall not be diminished.	PASSED
3.7.2. Resistance to solder	After flux coated, hold at ambient temperature for 5 minutes, preheat and solder float at 255±5°C for 10±1 seconds.	Solder shall not adhere to the solder mask.	PASSED

3.6.2. Hydrolytic Stability/Aging	97±2°C 90-98%RH 28 days.	No irreversible change of state.	PASSED
3.8.1. Dielectric Strength	Determined in accordance with TM2.5.6.1 of IPC-TM-650	Minimum value of 500 VDC per 0.025 mm [0.001 inch] of thickness.	PASSED 1.9KV/mil
3.8.2. Insulation Resistance	Minimum resistance of show before and after soldering.	Minimum $5 \times 10^8 \Omega$ at 500 VDC. IPC-B-25 test pattern B.	Before Soldering $2.30 \times 10^{13} \Omega$ After Soldering $2.50 \times 10^{12} \Omega$
3.9.1. Moisture and Insulation Resistance	25-65°C 85%RH Cycling 6 2/3 days Bias voltage 50 VDC and Test Voltage 100 VDC.	Minimum $5 \times 10^8 \Omega$ at 500 VDC. IPC-B-25 test pattern B.	Initial $1.8 \times 10^{13} \Omega$ After Treatment $1.6 \times 10^{12} \Omega$
3.9.2. Electromigration	85±2°C 90%RH 168 hours. Bias voltage 10VCD and Test Volatage 10VC	None allowed . Resistance \geq 2M Ω	PASSED
3.9.3. Thermal Shock	-65°C 15 min +125°C 15 min, Transition should not exceed 2 minutes. 100 cycles.	No blistering, crazing , and delamination.	PASSED